

Description

MLG20T65FUL is obtained by advanced Trench Field Stop (T-FS) technology which is characteristic with low VCE(sat), optimized switching performance and low gate charge Qg. The IGBT is suitable device for BLDC, UPS, and low VCE(sat) applications.

KEY CHARACTERISTICS

Parameter	Value	Unit
V _{CES}	650	V
I _C	20	A
V _{CE(sat).typ}	1.55	V

FEATURES

- ① Fast Switching
- ② Low VCE(sat)
- ③ Positive temperature coefficient
- ④ Very soft, fast recovery anti-parallel diode
- ⑤ RoHS product

APPLICATIONS

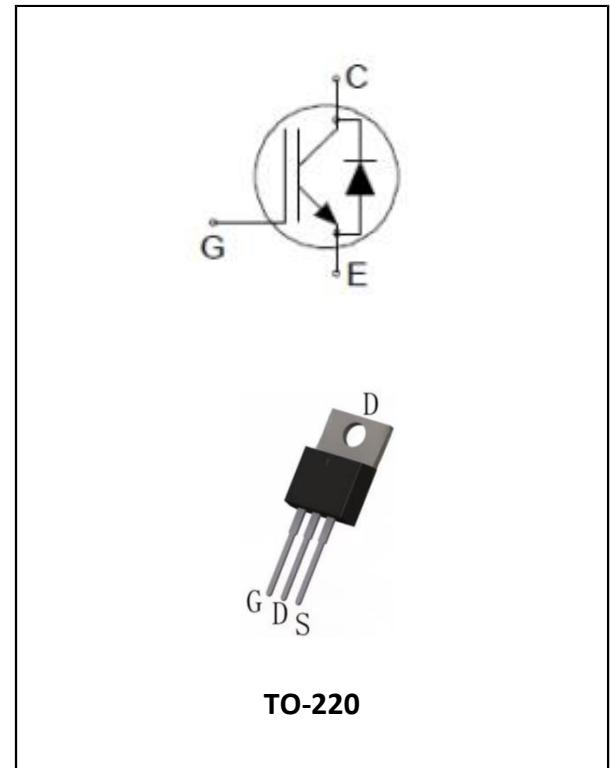
- ① UPS
- ② Motor drives
- ③ PFC
- ④ Portable power station

ORDERING INFORMATION

Ordering Codes	Package	Product Code	Packing
MLG20T65FUL	TO-220	MLG20T65FUL	Tube

ABSOLUTE RATINGS

Symbol	Parameter	TO-220	TO-220F	Units
V _{CES}	Collector-Emitter Voltage	650	650	V
I _C	Collector Current @T _C =25°C	40	40	A
	Collector Current @T _C =100°C	20	20	A
I _{CM}	Pulsed Collector Current, tp limited by T _{Jmax}	80	80	A





迈诺斯科技

MLG20T65FUL

I _F	Diode Continuous Forward Current @T _c =25°C	40	40	A
	Diode Continuous Forward Current @T _c =100°C	20	20	A
I _{FM}	Diode Maximum Forward Current, limited by T _{jmax}	40	40	A
V _{GES}	Gate-Emitter Voltage	±30	±30	V
t _{sc}	Short circuit withstand time V _{GE} =15V, V _{CC} ≤400V, Allowed number of short circuits<1000,Times between short circuits: ≥ 1.0s,T _j ≤ 175°C	3.0		us
P _D	Power Dissipation @T _c =25°C	136	39	W
T _{jmax} , T _{stg}	Operating Junction and Storage Temperature Range	175, -55 to 175		°C
T _L	Maximum Temperature for Soldering	260		°C

Thermal characteristics

Symbol	Parameter	TO-220	TO-220F	Units
R _{θJC}	Junction-to-Case (IGBT)	1.1	3.8	°C/W
R _{θJC}	Junction-to-Case (Diode)	2.4	6.8	°C/W
R _{θJA}	Junction-to-Ambient	62.5	78	°C/W

Electrical Characteristics at TC = 25°C, unless otherwise specified

Static Characteristics

Symbol	Parameter	Test Conditions	Values			Units
			Min.	Typ.	Max.	
V _{CES}	Collector-Emitter Breakdown Voltage	V _{GE} = 0V, I _C = 250μA	650	--	--	V
V _{CE(sat)}	Collector-Emitter Saturation Voltage	V _{GE} = 15V, I _C = 20A T _j =25°C T _j =125°C T _j =175°C	-- -- --	1.55 1.80 1.90	1.95 -- --	V
V _{GE(TH)}	Gate Threshold Voltage	V _{CE} = V _{GE} , I _C = 1mA	5.1	5.8	6.5	V
V _F	Diode Forward Voltage	I _F =10A T _j =25°C T _j =125°C T _j =175°C	-- -- --	1.60 1.40 1.30	2.20 -- --	V
V _F	Diode Forward Voltage	I _F =20A T _j =25°C T _j =125°C T _j =175°C	-- -- --	1.90 1.75 1.65	2.50 -- --	V
I _{CES}	Collector-Emitter Leakage Current	V _{CE} = 650V, V _{GE} = 0V	--	--	4	μA
I _{GES(F)}	Gate-Emitter Leakage Current	V _{GE} = +30V	--	--	200	nA
I _{GES(R)}	Gate-Emitter Reverse Leakage	V _{GE} = -30V	--	--	-200	nA



迈诺斯科技

MLG20T65FUL

Pulse width $t_p \leq 300\mu s$, $\delta \leq 2\%$

Dynamic Characteristics

Symbol	Parameter	Test Conditions	Values			Units
			Min.	Typ.	Max.	
C_{iss}	Input Capacitance	$V_{GE}=0V$ $V_{CE}=25V$ $f=1.0MHz$	--	892	--	pF
C_{oss}	Output Capacitance		--	43	--	
C_{rss}	Reverse Transfer Capacitance		--	10	--	
Q_G	Gate charge	$V_{CC}=520V$ $I_{CE}=20A$ $V_{GE}=15V$	--	44	--	nC
Q_{GE}	Gate-emitter charge		--	13	--	
Q_{GC}	Gate-collector charge		--	18	--	
$I_{C(SC)}$	Short circuit collector current Max.1000 short circuits, Times between short circuits: $\geq 1.0s$	$V_{GE}=15.0V, V_{CC}\leq 400V,$ $t_{SC}\leq 3\mu s, T_J\leq 175^{\circ}C$		110		A

IGBT Switching Characteristics, at $T_J=25^{\circ}C$

Symbol	Parameter	Test Conditions	Values			Units
			Min.	Typ.	Max.	
$t_{d(on)}$	Turn-on Delay Time	$I_C=20A$ $V_{CE} = 400V$ $V_{GE} = 15V$ $R_G = 10\Omega$ $T_J=25^{\circ}C$ Inductive Load	--	15	--	ns
t_r	Rise Time		--	24	--	
$t_{d(off)}$	Turn-Off Delay Time		--	75	--	
t_f	Fall Time		--	86	--	
E_{on}	Turn-On Switching Loss		--	0.50	--	mJ
E_{off}	Turn-Off Switching Loss		--	0.27	--	
E_{ts}	Total Switching Loss		--	0.77	--	

IGBT Switching Characteristics, at $T_J=175^{\circ}C$

Symbol	Parameter	Test Conditions	Values			Units
			Min.	Typ.	Max.	
$t_{d(on)}$	Turn-on Delay Time	$I_C = 20A$ $V_{CE} = 400V$ $V_{GE} = 15V$ $R_G = 10\Omega$ $T_J=175^{\circ}C$ Inductive Load	--	14	--	ns
t_r	Rise Time		--	23	--	
$t_{d(off)}$	Turn-Off Delay Time		--	96	--	
t_f	Fall Time		--	128	--	
E_{on}	Turn-On Switching Loss		--	0.54	--	mJ
E_{off}	Turn-Off Switching Loss		--	0.49	--	
E_{ts}	Total Switching Loss		--	1.03	--	

Diode Characteristics, at $T_J=25^{\circ}C$

Symbol	Parameter	Test Conditions	Values			Units
			Mi	Typ.	Max.	



迈诺斯科技

MLG20T65FUL

T _{rr}	Reverse Recovery Time	I _F =10A, di/dt=200A/us, T _J =25°C	--	66	--	ns
Q _{rr}	Reverse Recovery Charge		--	182	--	nC
I _{rrm}	Reverse Recovery Current		--	4.5	--	A
T _{rr}	Reverse Recovery Time	I _F =20A, di/dt=200A/us, T _J =25°C	--	75	--	ns
Q _{rr}	Reverse Recovery Charge		--	236	--	nC
I _{rrm}	Reverse Recovery Current		--	5.4	--	A

Diode Characteristics, at T_J=175°C

Symbol	Parameter	Test Conditions	Values			Units
			Min.	Typ.	Max.	
T _{rr}	Reverse Recovery Time	I _F =10A, di/dt=200A/us, T _J =175°C	--	122	--	ns
Q _{rr}	Reverse Recovery Charge		--	690	--	nC
I _{rrm}	Reverse Recovery Current		--	10.0	--	A
T _{rr}	Reverse Recovery Time	I _F =20A, di/dt=200A/us, T _J =175°C	--	150	--	ns
Q _{rr}	Reverse Recovery Charge		--	910	--	nC
I _{rrm}	Reverse Recovery Current		--	11.0	--	A

Characteristics Curves

Figure 1. Forward Bias Safe Operating Area for TO220

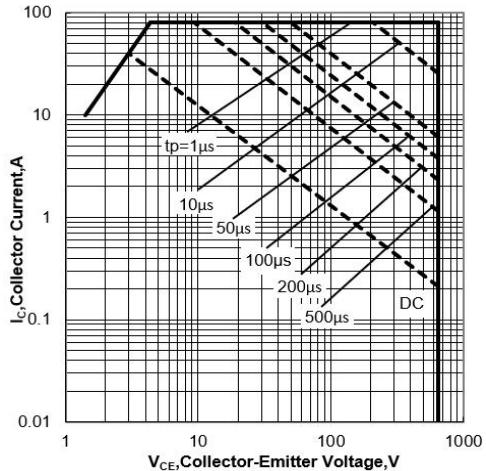


Figure 2. Forward Bias Safe Operating Area for TO220F

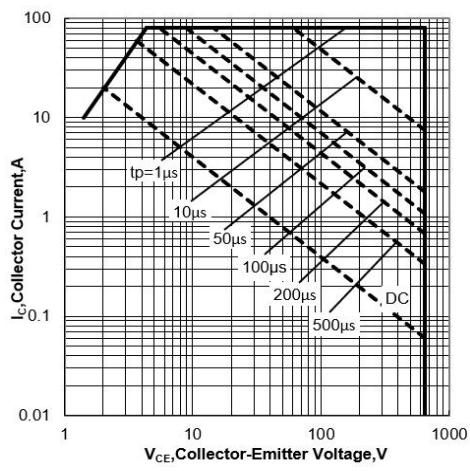


Figure 3. Power Dissipation vs Case Temperature for TO220

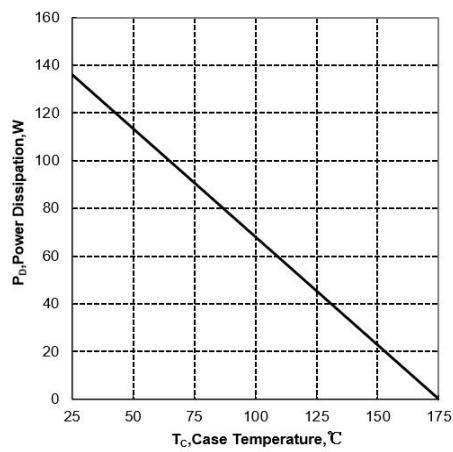


Figure 4. Power Dissipation vs Case Temperature for TO220F

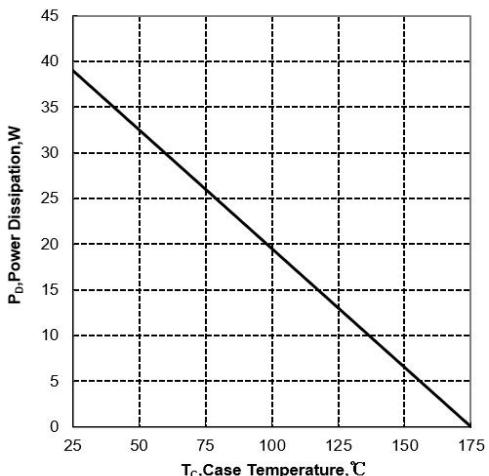


Figure 5. Collector Current vs Case Temperature

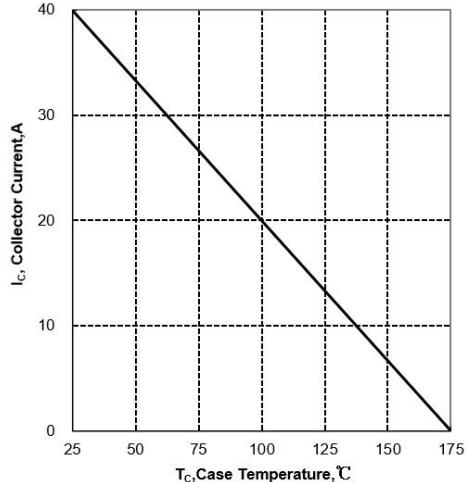


Figure 6. Typical Transfer Characteristics

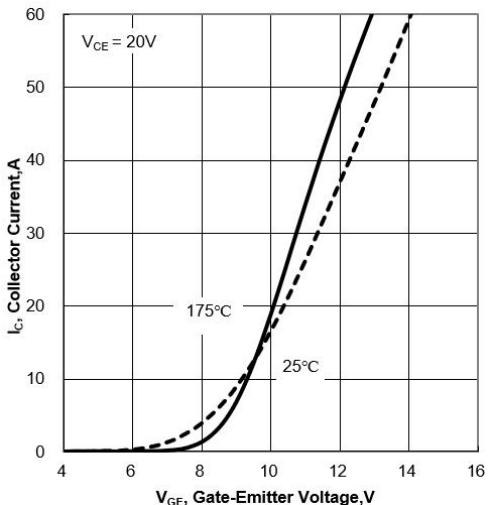


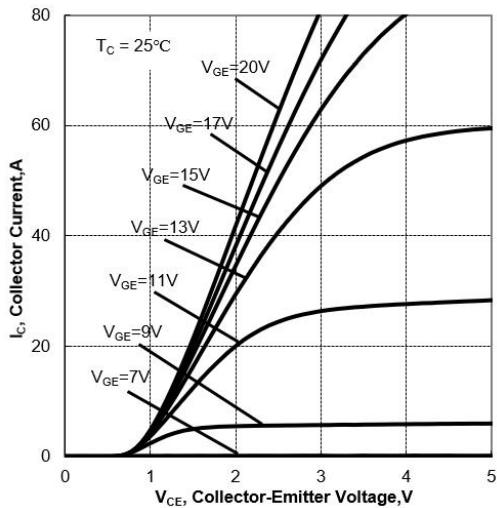
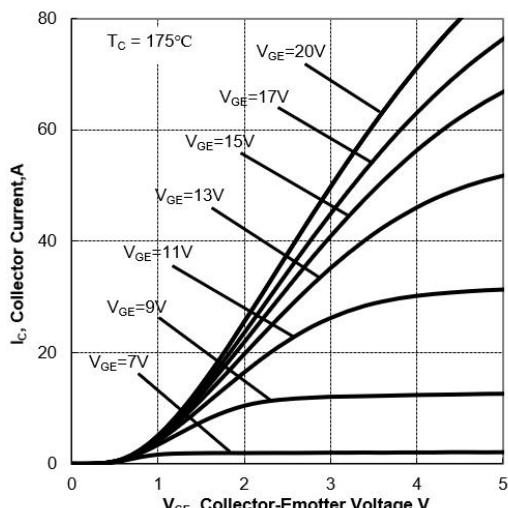
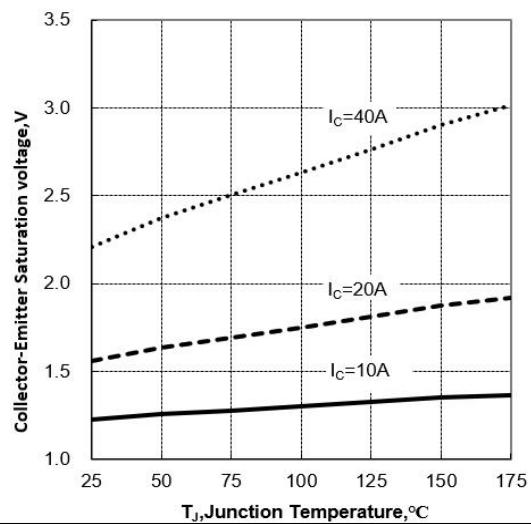
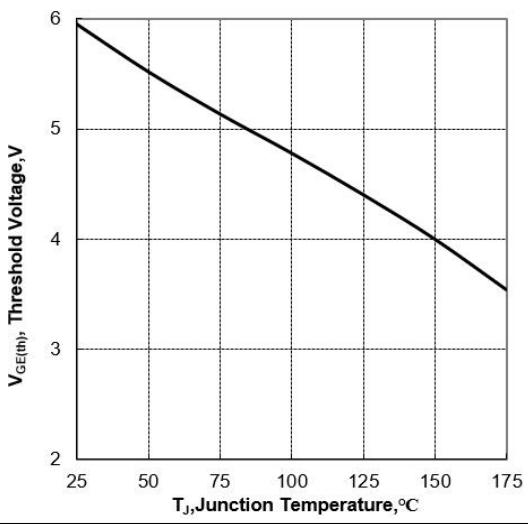
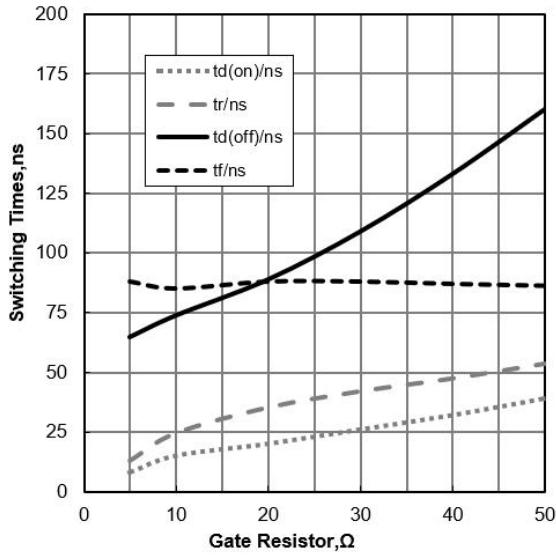
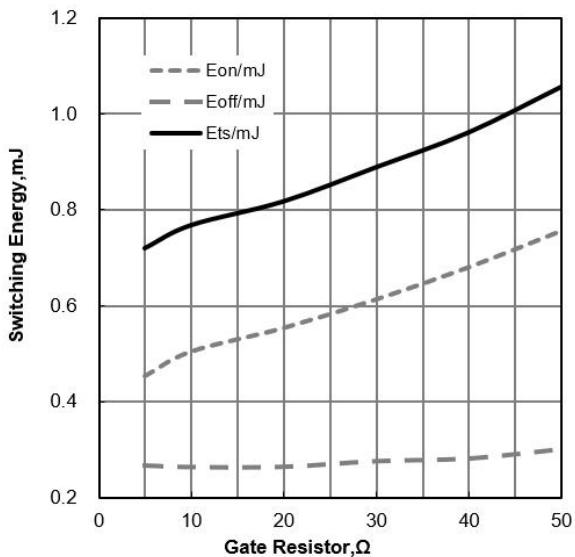
Figure 7. Typical Output Characteristics ($T_c=25^\circ\text{C}$)

Figure 8. Typical Output Characteristics ($T_c=175^\circ\text{C}$)

Figure 9. Typical Collector-Emitter Saturation Voltage vs Case Temperature

Figure 10. Typical Gate-Emitter Threshold Voltage vs Case Temperature

Figure 11. Typical Switching Times vs Gate Resistor ($T_j=25^\circ\text{C}$, $V_{ce}=400\text{V}$, $V_{ge}=15/0\text{V}$, $I_c=20\text{A}$)

Figure 12. Typical Switching Energy vs Gate Resistor ($T_j=25^\circ\text{C}$, $V_{ce}=400\text{V}$, $V_{ge}=15/0\text{V}$, $I_c=20\text{A}$)


Figure 13. Typical Switching Times vs Case Temperature (Vce=400V, Vge=15/0V, Ic=20A)

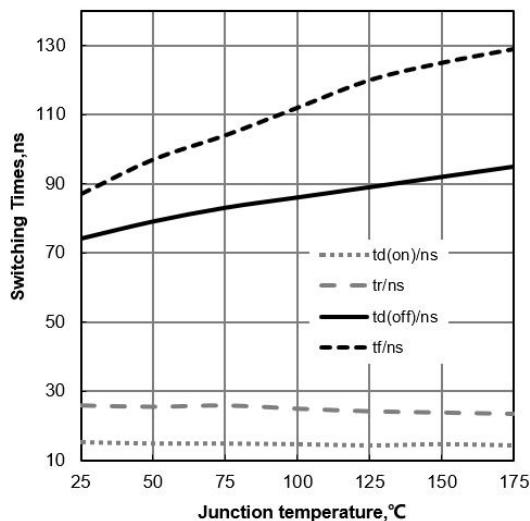


Figure 14. Typical Switching Energy vs Case Temperature (Vce=400V, Vge=15/0V, Ic=20A)

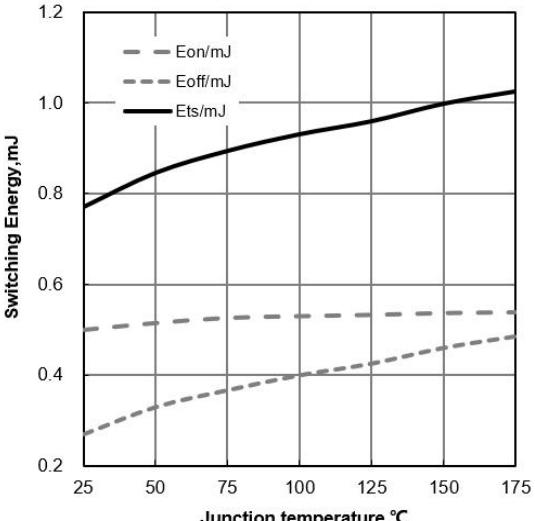


Figure 15. Typical Switching Times vs Collector Current (Tc=25°C, Vce=400V, Vge=15/0V)

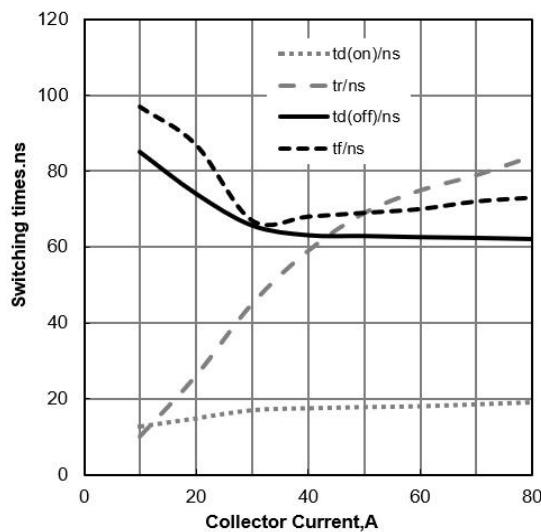


Figure 16. Typical Switching Energy vs Collector Current (Tc=25°C, Vce=400V, Vge=15/0V)

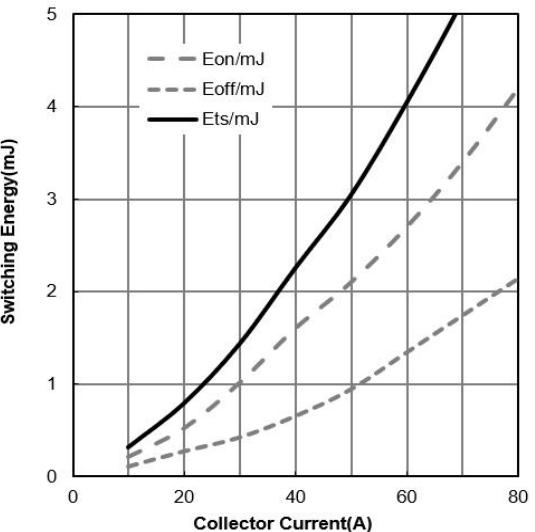


Figure 17. Typical Switching Times vs Vce (Tc=25°C, Vge=15/0V, Ic=20A)

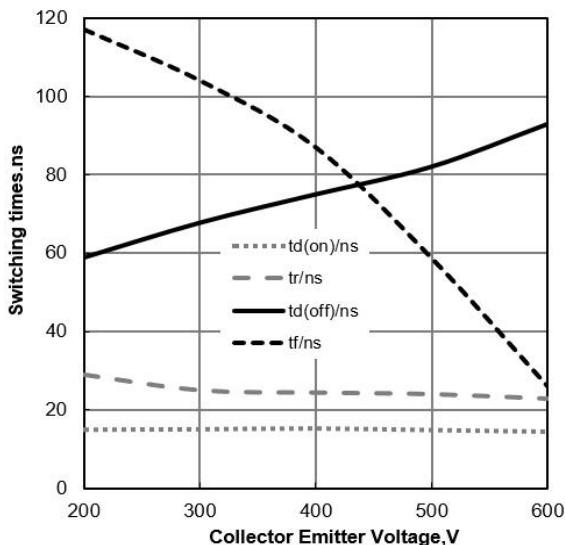


Figure 18. Typical Switching Energy vs Vce (Tc=25°C, Vge=15/0V, Ic=20A)

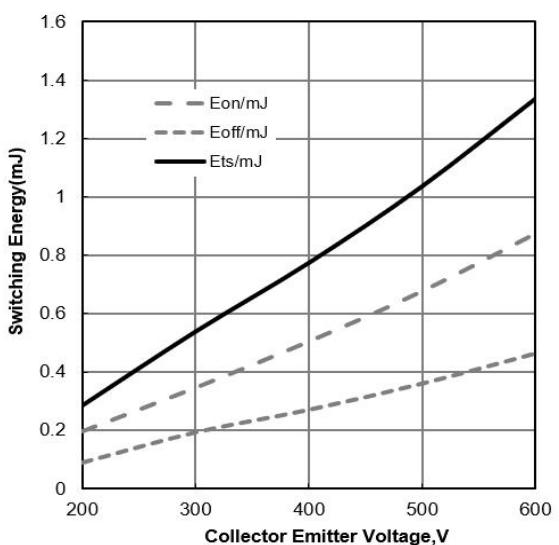


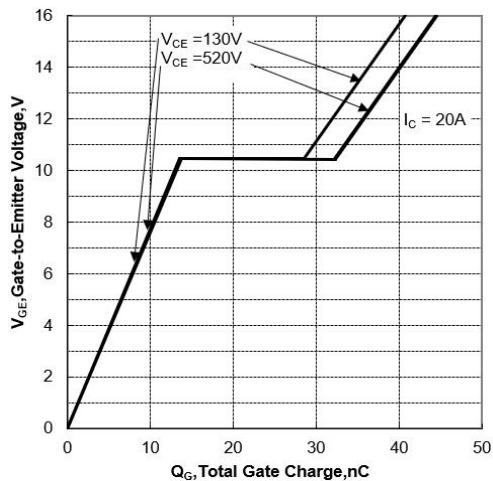
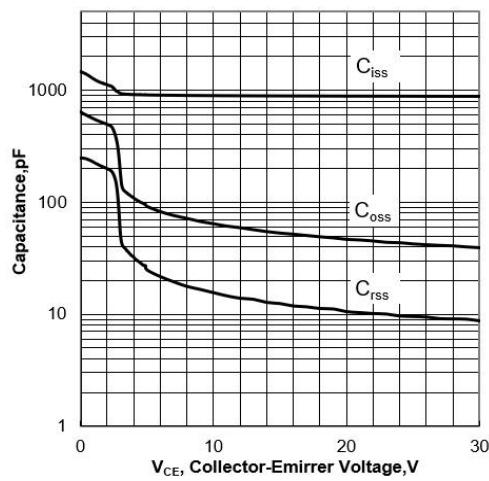
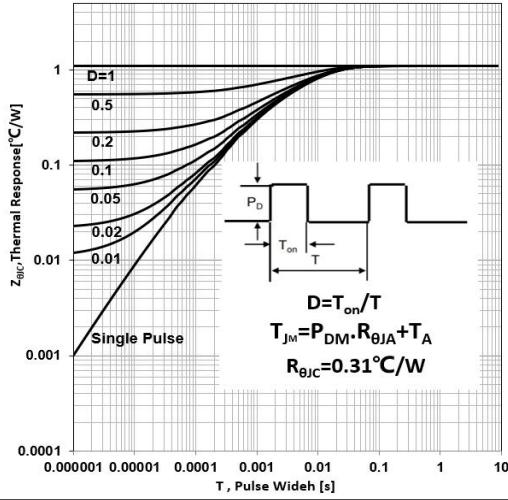
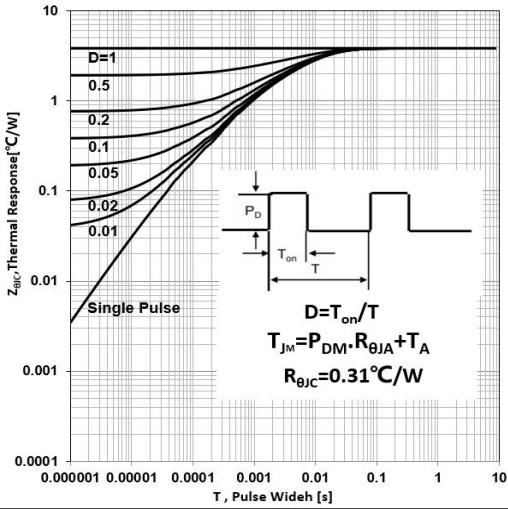
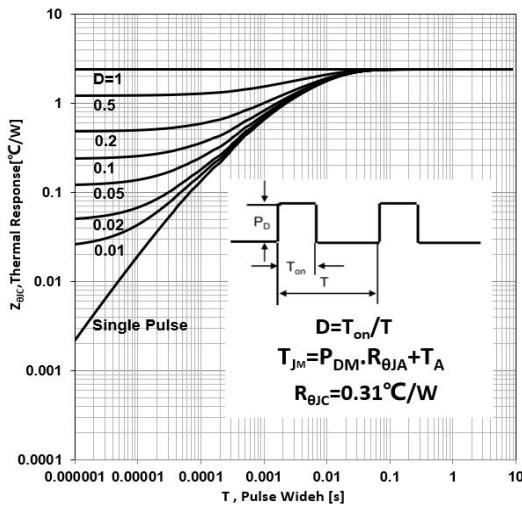
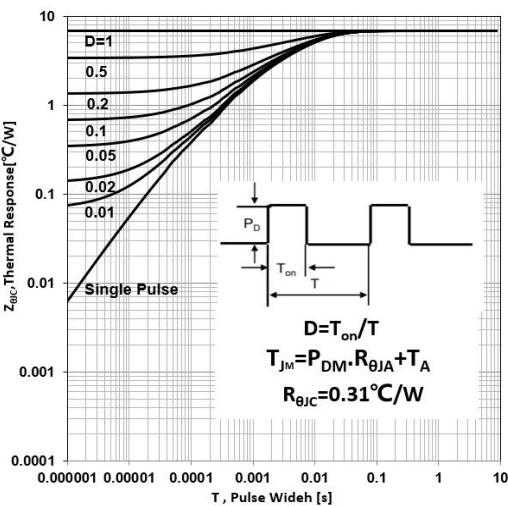
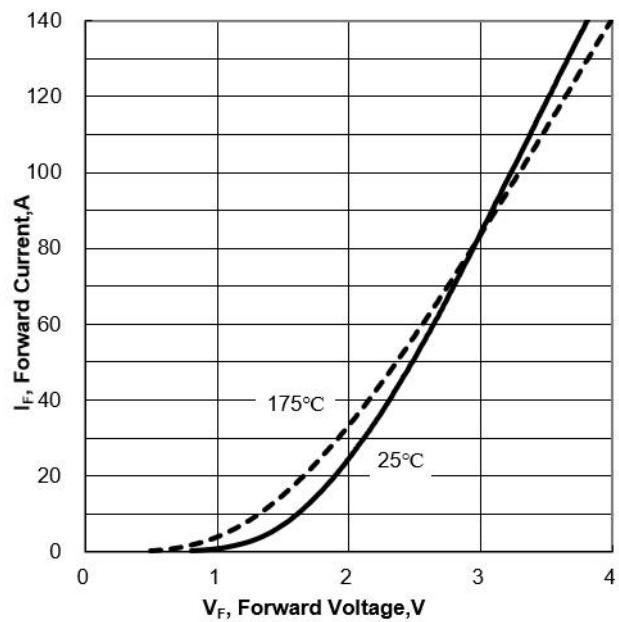
Figure 19. Typical Gate Charge

Figure 20. Typical Capacitance vs Collector-Emitter Voltage

Figure 21. IGBT Transient Thermal Impedance vs Pulse Width(TO220)

Figure 22. IGBT Transient Thermal Impedance vs Pulse Width(TO220F)

Figure 23. Diode Transient Thermal Impedance vs Pulse Width(TO220)

Figure 24. Diode Transient Thermal Impedance vs Pulse Width(TO220F)


Figure 25. Typical Diode Forward Current vs Forward Voltage



Test Circuit and Waveform

Figure 11. Inductive Switching Test Circuit

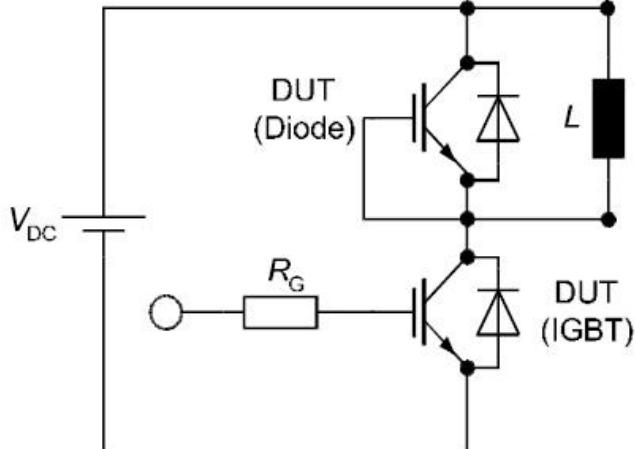


Figure 12. Definition of switching times

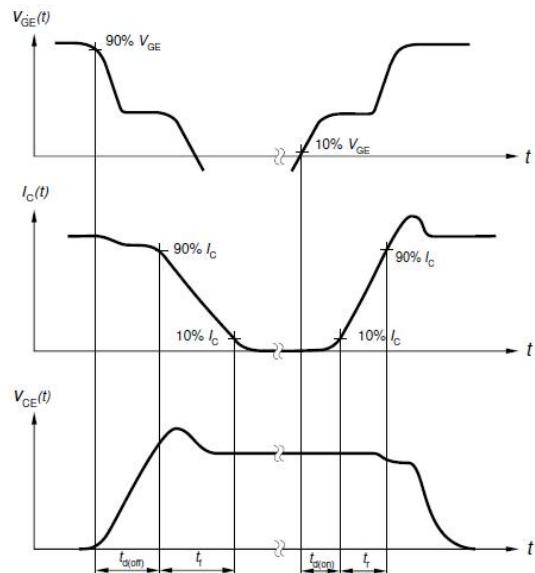


Figure 13. Definition of switching losses

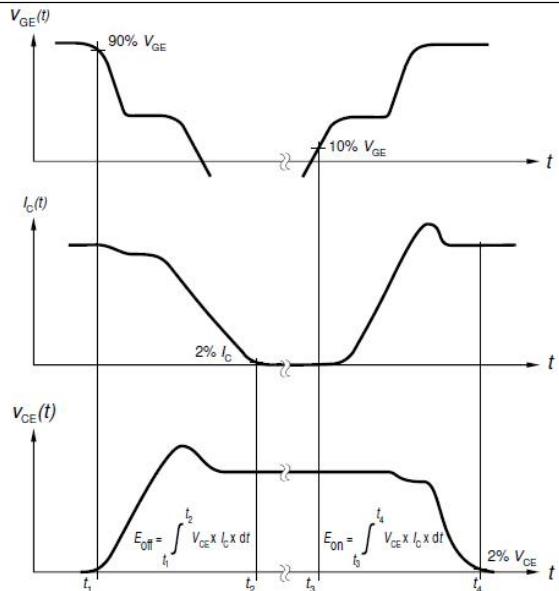
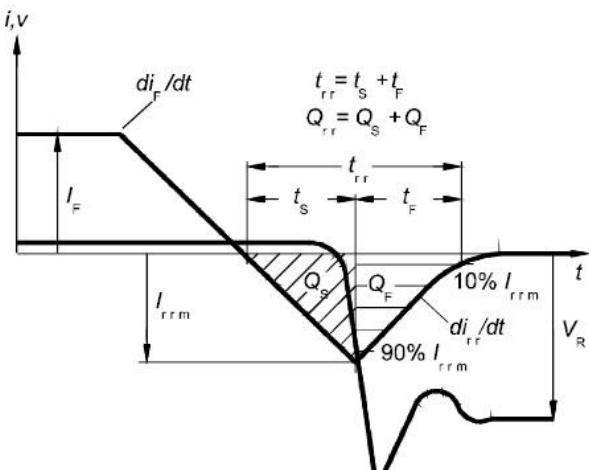
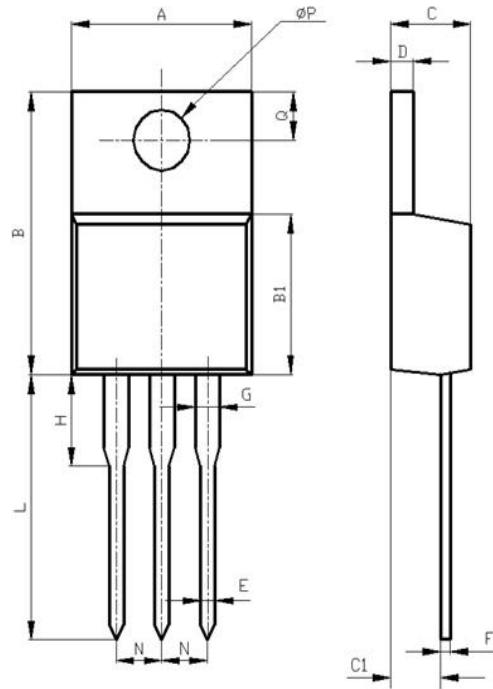


Figure 14. Definition of diode switching characteristics



Package Description



Items	Values(mm)	
	MIN	MAX
A	9.60	10.6
B	15.0	16.0
B1	8.90	9.50
C	4.30	4.80
C1	2.30	3.10
D	1.20	1.40
E	0.70	0.90
F	0.30	0.60
G	1.17	1.37
H	2.70	3.80
L	12.6	14.8
N	2.34	2.74
Q	2.40	3.00
ϕP	3.50	3.90

TO-220 Package



迈诺斯科技

MLG20T65FUL

NOTE:

1. Exceeding the maximum ratings of the device in performance may cause damage to the device, even the permanent failure, which may affect the dependability of the machine. Please do not exceed the absolute maximum ratings of the device when circuit designing.
2. When installing the heat sink, please pay attention to the torsional moment and the smoothness of the heat sink.
3. MOSFETs is the device which is sensitive to the static electricity, it is necessary to protect the device from being damaged by the static electricity when using it.
4. Shenzhen Minos reserves the right to make changes in this specification sheet and is subject to change without prior notice.

CONTACT:

深圳市迈诺斯科技有限公司（总部）

地址：深圳市福田区华富街道田面社区深南中路4026号田面城市大厦22B-22C

邮编：518025

电话：0755-83273777

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Minos manufacturer:

Other Similar products are found below :

[2SA1837](#) [2SA1941](#) [2SA1943](#) [2SC4793](#) [2SC5198](#) [2SC5200](#) [78M05](#) [78M12](#) [A940](#) [AO3400S](#) [AO3401S](#) [AP8012H](#) [AP8022H](#) [AP8022HS](#) [B772](#) [BT134-600E](#) [BT134S-600E](#) [BT134W](#) [BT136-600E](#) [BT136S-600E](#) [BT136S-800E](#) [BT137-600E](#) [BT139-600E](#) [BT139-800E](#) [BTA04-600B](#) [BTA12-600B](#) [BTA12-800B](#) [BTA16-600B](#) [BTA16-800B](#) [BTA41-600B](#) [BTB04-600B](#) [BTB06-600B](#) [BTB08-600B](#) [BTB12-600B](#) [BTB20-600B](#) [C2073](#) [D882](#) [IRF1405](#) [IRF1407](#) [IRF3205](#) [IRF3205S](#) [IRF3710](#) [IRF3710STR](#) [IRF5210](#) [IRF530](#) [IRF540N](#) [IRF540NS](#) [IRF630N](#) [IRF640](#) [IRF740](#)